

CM1405

LCD EMI Filter Array with ESD Protection

Description

ON Semiconductor's CM1405 is an EMI filter array with ESD protection, which integrates eight Pi- filters (C-R-C). The CM1405 has component values of 25 pF – 100 Ω – 25 pF. The parts include avalanche-type ESD diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD diodes connected to the filter ports safely dissipate ESD strikes of ± 30 kV, exceeding the maximum requirement of the IEC61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ± 30 kV.

This device is particularly well-suited for portable electronics (e.g. mobile handsets, PDAs, notebook computers) because of its small package and easy-to-use pin assignments. In particular, the CM1405 is ideal for EMI filtering and protecting data lines from ESD for the LCD display in mobile handsets.

The CM1405-03 incorporates *OptiGuard*[™] coating which results in improved reliability at assembly and is available in a space-saving, low-profile Chip Scale Package with RoHS compliant lead-free finishing.

Features

- Eight Channels of EMI Filtering
- ± 30 kV ESD Protection on Each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- ± 30 kV ESD Protection on Each Channel (HBM)
- Better than 35 dB of Attenuation at 800-2700 MHz
- Chip Scale Package Features Extremely Low Lead Inductance for Optimum Filter and ESD Performance
- 20-Bump, 4.000 mm x 1.458 mm Footprint Chip Scale Package
- *OptiGuard*[™] Coated Version Available for Improved Reliability at Assembly
- These Devices are Pb-Free and are RoHS Compliant

Applications

- LCD Data Lines in Mobile Handsets
- EMI Filtering & ESD Protection for High-Speed I/O Ports
- EMI Filtering for High-Speed Data Lines
- Wireless Handsets
- Cell Phones
- Notebook Computers
- PDAs / Handheld PCs



ON Semiconductor®

<http://onsemi.com>



**WLCSP20
CP SUFFIX
CASE 567BZ**

MARKING DIAGRAM

N051	N053
CM1405-01 20-Bump CSP Package	CM1405-03 20-Bump CSP Package
N051 = CM1405-01CP	
N053 = CM1405-03CP	

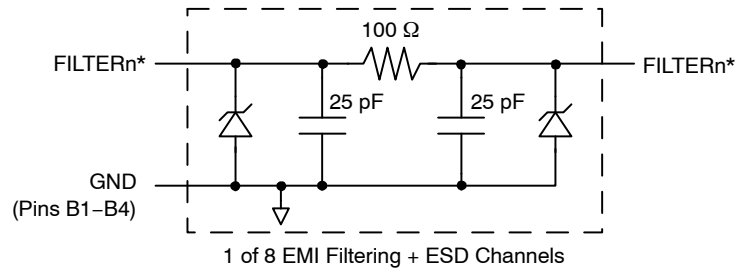
ORDERING INFORMATION

Device	Package	Shipping [†]
CM1405-01CP	CSP-20 (Pb-Free)	3500/Tape & Reel
CM1405-03CP	CSP-20 (Pb-Free)	3500/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

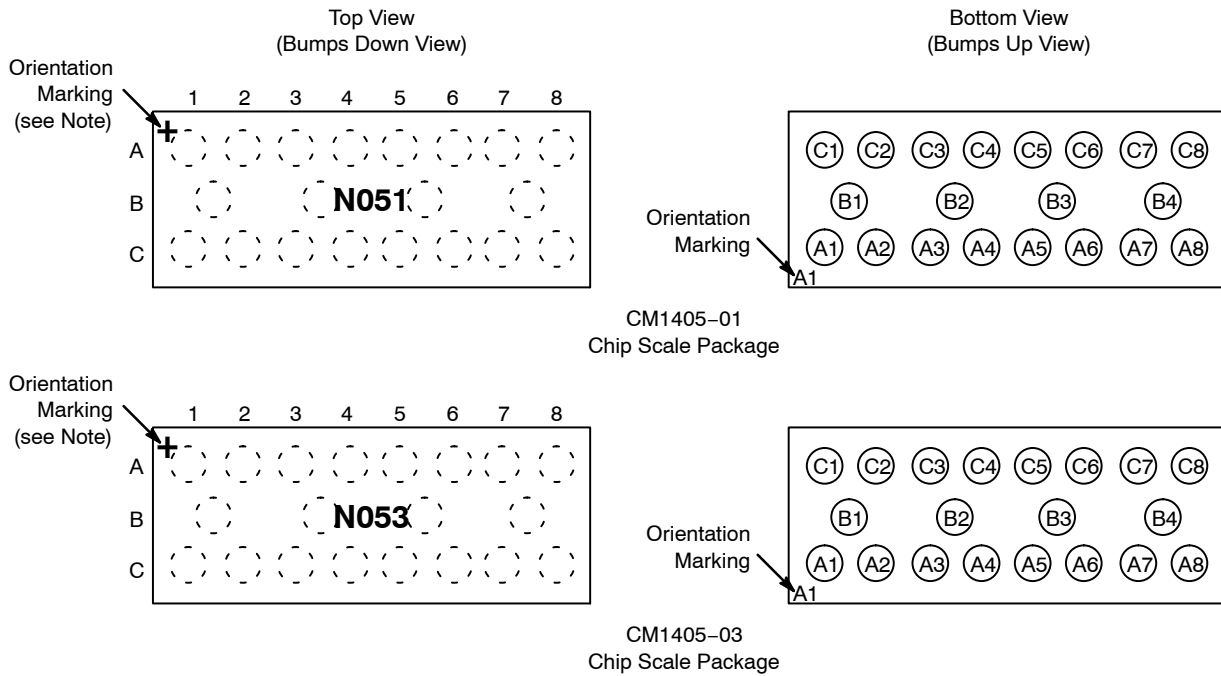
CM1405

BLOCK DIAGRAM



*See Package/Pinout Diagrams for expanded pin information.

PACKAGE / PINOUT DIAGRAMS



Note: Lead-free devices are specified by using a "+" character for the top side orientation mark.

Table 1. PIN DESCRIPTIONS

Pins	Name	Description	Pins	Name	Description
A1	FILTER1	Filter Channel 1	C1	FILTER1	Filter Channel 1
A2	FILTER2	Filter Channel 2	C2	FILTER2	Filter Channel 2
A3	FILTER3	Filter Channel 3	C3	FILTER3	Filter Channel 3
A4	FILTER4	Filter Channel 4	C4	FILTER4	Filter Channel 4
A5	FILTER5	Filter Channel 5	C5	FILTER5	Filter Channel 5
A6	FILTER6	Filter Channel 6	C6	FILTER6	Filter Channel 6
A7	FILTER7	Filter Channel 7	C7	FILTER7	Filter Channel 7
A8	FILTER8	Filter Channel 8	C8	FILTER8	Filter Channel 8
B1-B4	GND	Device Ground			

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
DC Power per Resistor	100	mW
DC Package Power Rating	500	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
R	Resistance		80	100	120	Ω
C	Capacitance	At 2.5 V DC, 1 MHz, 30 mV AC	20	25	30	pF
V _{DIODE}	Diode Standoff Voltage	I _{DIODE} = 10 μ A		6.0		V
I _{LEAK}	Diode Leakage Current (reverse bias)	V _{DIODE} = +3.3 V		0.1	1	μ A
V _{SIG}	Signal Clamp Voltage Positive Clamp Negative Clamp	I _{LOAD} = 10 mA I _{LOAD} = -10 mA	5.6 -1.5	6.8 -0.8	9.0 -0.4	V
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	(Note 2)	30 30			kV
R _{DYN}	Dynamic Resistance Positive Negative			1.5 0.9		Ω
f _C	Cut-off Frequency Z _{SOURCE} = 50 Ω , Z _{LOAD} = 50 Ω	R = 100 Ω , C = 25 pF		70		MHz

1. T_A = 25 °C unless otherwise specified.

2. ESD applied to input and output pins with respect to GND, one at a time.

PERFORMANCE INFORMATION

Typical Filter Performance (nominal conditions unless specified otherwise, 50 Ω Environment)

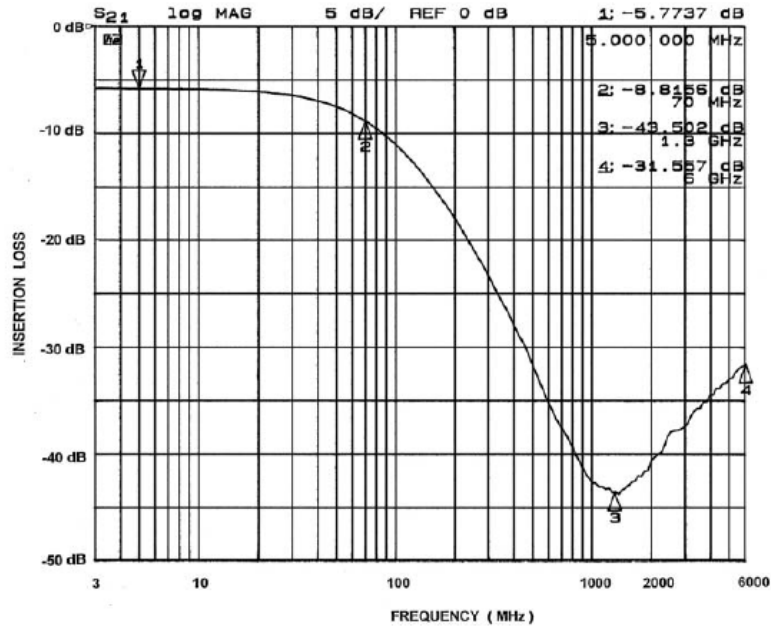


Figure 1. A1-C1 EMI Filter Performance

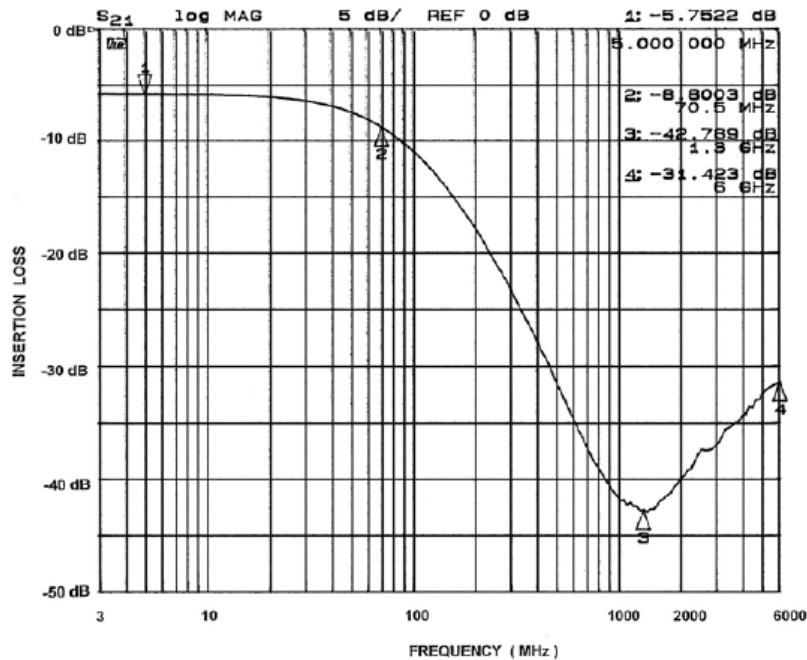


Figure 2. A2-C2 EMI Filter Performance

PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance (nominal conditions unless specified otherwise, 50 Ω Environment)

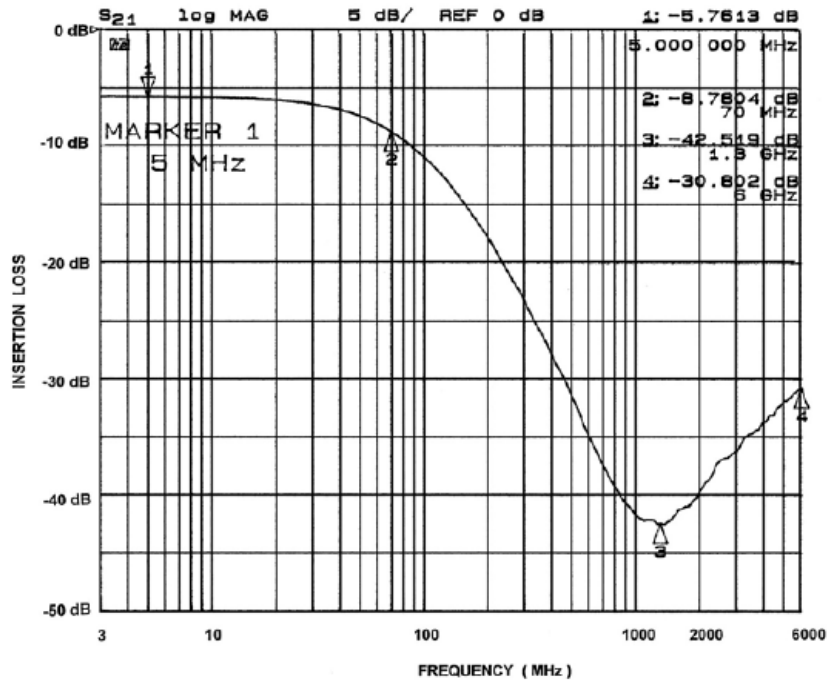


Figure 3. A3-C3 EMI Filter Performance

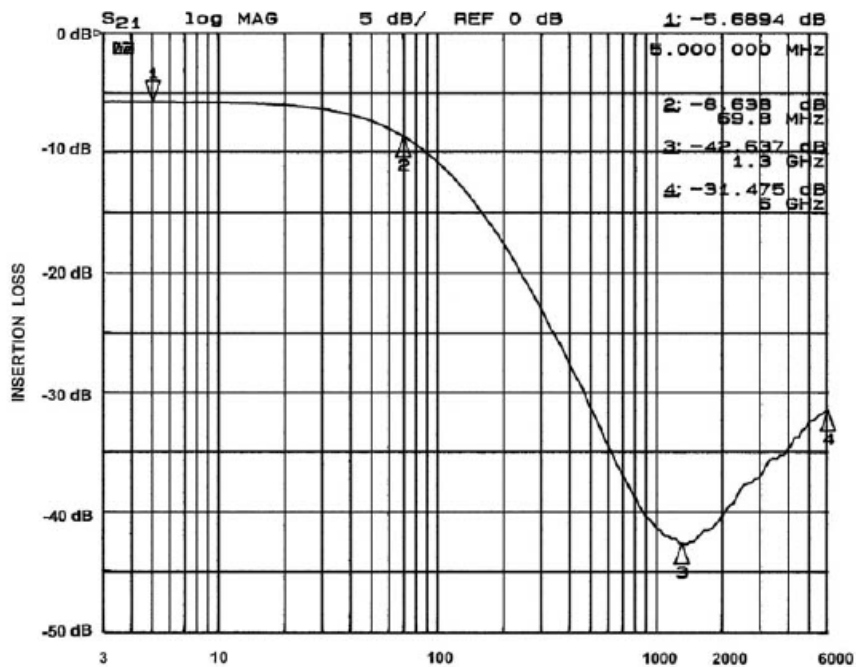


Figure 4. A4-C4 EMI Filter Performance

PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance (nominal conditions unless specified otherwise, 50 Ω Environment)

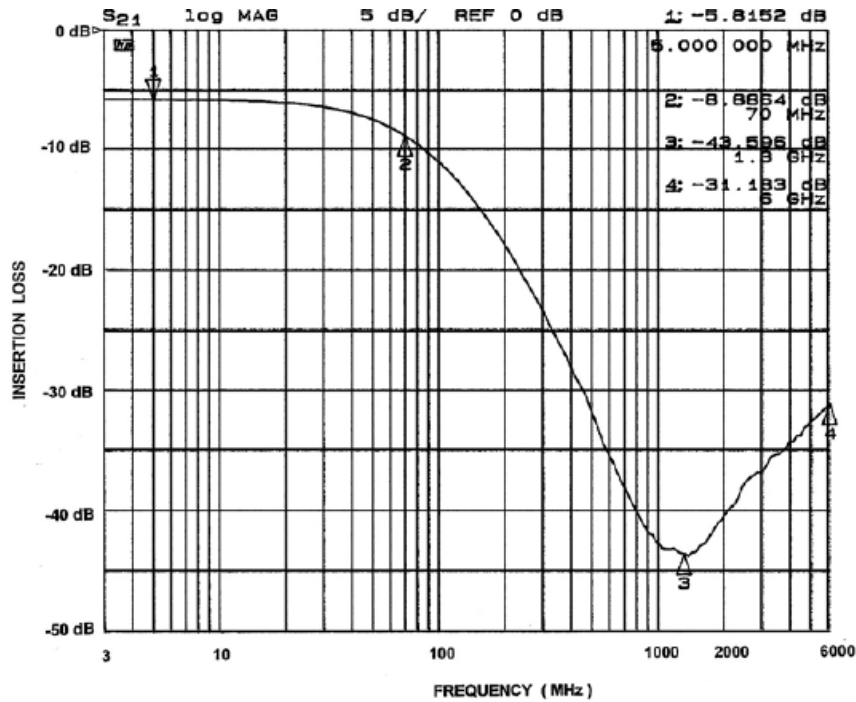


Figure 5. A5-C5 EMI Filter Performance

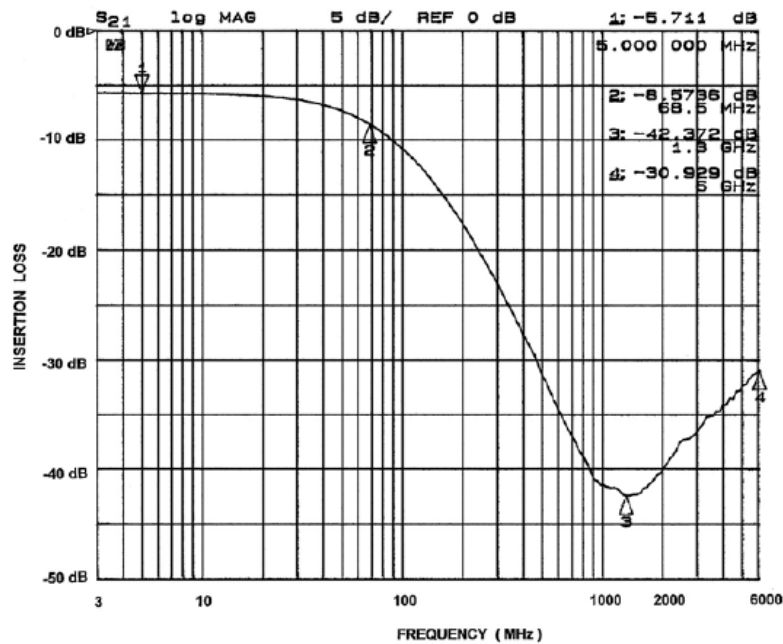


Figure 6. A6-C6 EMI Filter Performance

PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance (nominal conditions unless specified otherwise, 50 Ω Environment)

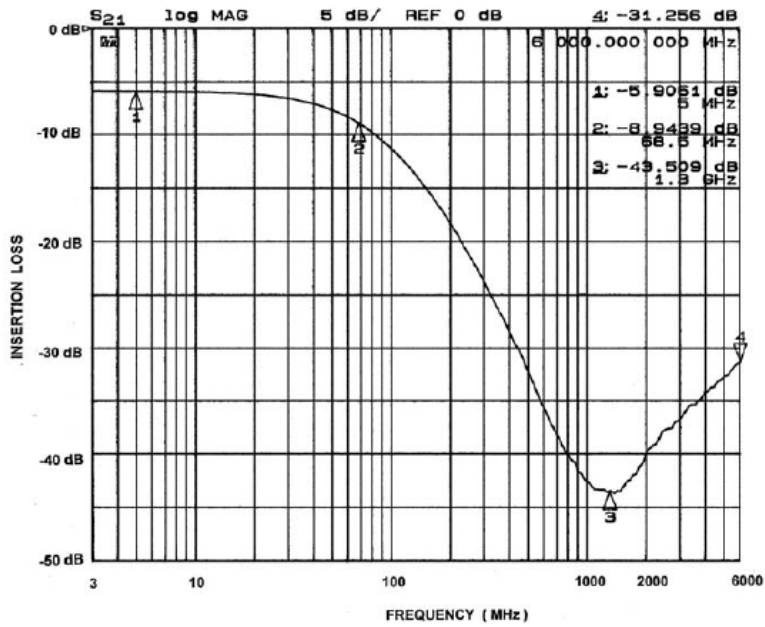


Figure 7. A7-C7 EMI Filter Performance

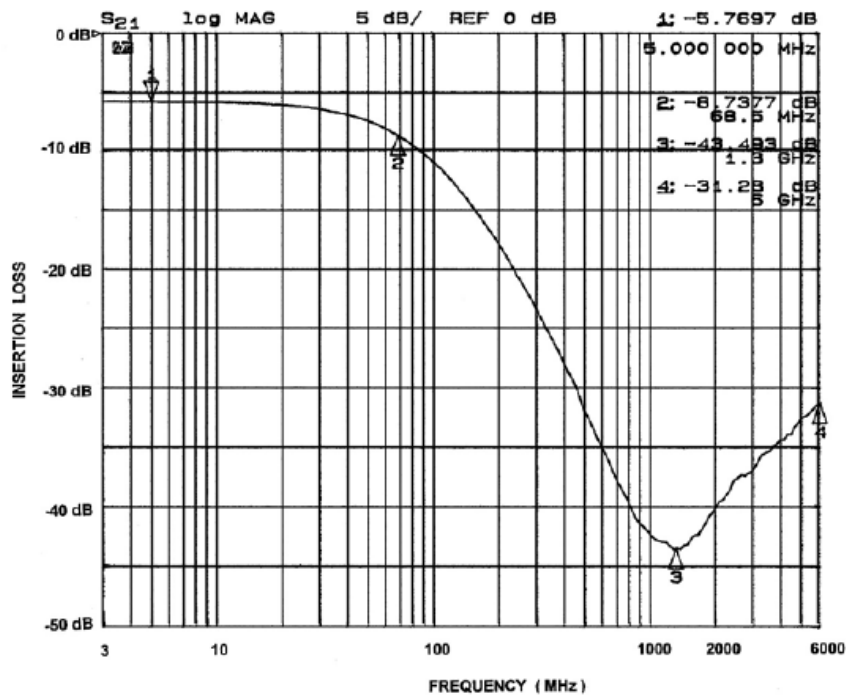


Figure 8. A8-C8 EMI Filter Performance

PERFORMANCE INFORMATION (Cont'd)

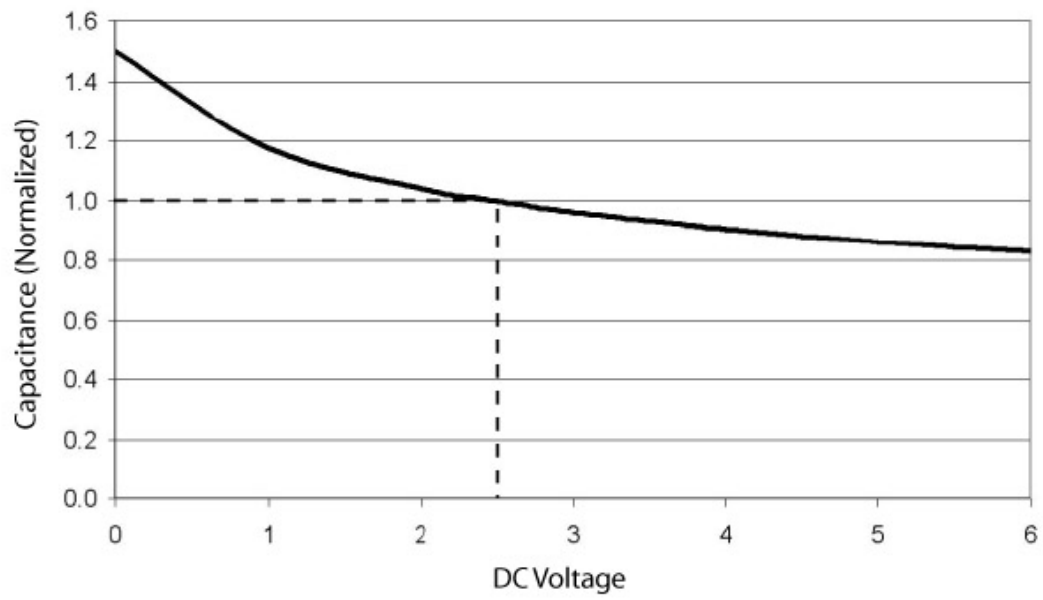


Figure 9. Filter Capacitance vs. Input Voltage over Temperature
(normalized to capacitance at 2.5 VDC and 25°C)

APPLICATION INFORMATION

Table 5. PRINTED CIRCUIT BOARD RECOMMENDATIONS

Parameter	Value
Pad Size on PCB	0.240 mm
Pad Shape	Round
Pad Definition	Non-Solder Mask defined pads
Solder Mask Opening	0.290 mm Round
Solder Stencil Thickness	0.125 – 0.150 mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.300 mm Round
Solder Flux Ratio	50/50 by volume
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance – Edge To Corner Ball	$\pm 50\ \mu\text{m}$
Solder Ball Side Coplanarity	$\pm 20\ \mu\text{m}$
Maximum Dwell Time Above Liquidous (183°C)	60 seconds
Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste	260°C

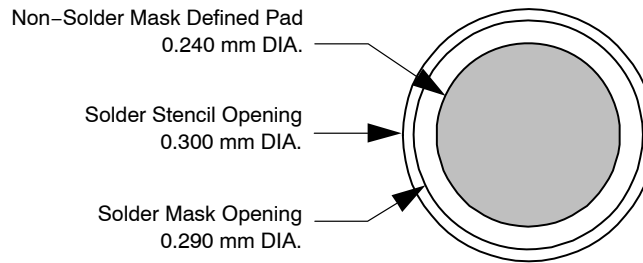


Figure 10. Recommended Non-Solder Mask Defined Pad Illustration

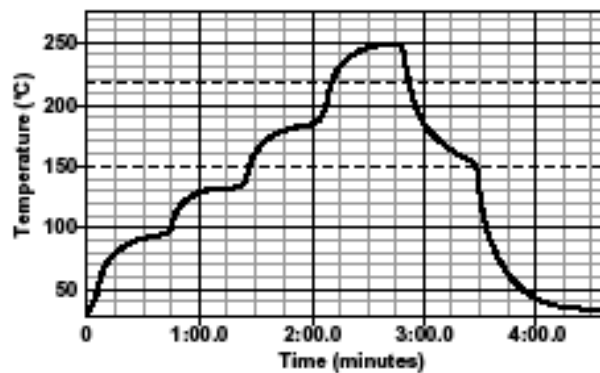


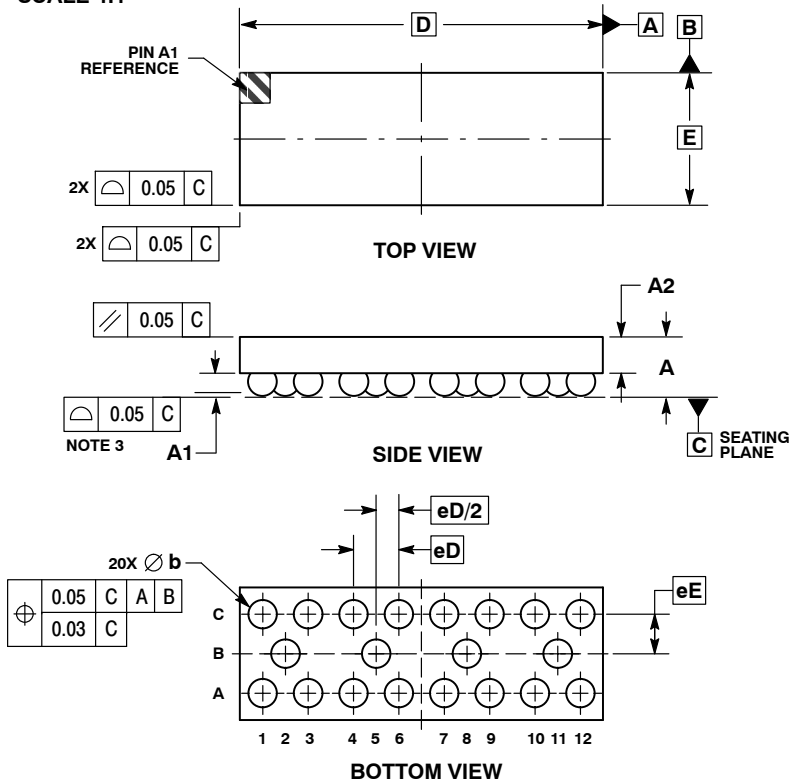
Figure 11. Lead-free (SnAgCu) Solder Ball Reflow Profile



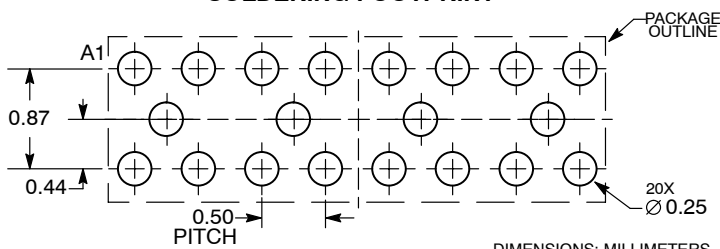
WLCSP20, 4.00x1.46
CASE 567BZ
ISSUE O

DATE 26 JUL 2010

SCALE 4:1



RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.65
A1	0.21	0.27
A2	0.40 REF	
b	0.29	0.35
D	4.00 BSC	
E	1.46 BSC	
eD	0.50 BSC	
eE	0.435 BSC	

DOCUMENT NUMBER:	98AON49833E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	WLCSP20, 4.00X1.46	PAGE 1 OF 1

onsemi and **onsemi** are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at
www.onsemi.com/support/sales